

HZN6.8ZMFA

Silicon Planar Zener Diode for Surge Absorb

HITACHI

ADE-208-1456 (Z)

Rev.0
Nov. 2001

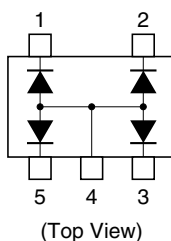
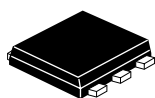
Features

- HZN6.8ZMFA has four devices in a monolithic, and can absorb surge.
- VSON-5 Package is suitable for high density surface mounting.

Ordering Information

Type No.	Laser Mark	Package Code
HZN6.8ZMFA	68*(* : Let to Month Code)	VSON-5

Pin Arrangement



(Top View)

1. Cathode
2. Cathode
3. Cathode
4. Anode
5. Cathode

Absolute Maximum Ratings

(Ta = 25°C)

Item	Symbol	Value	Unit
Power dissipation	Pd * ¹	150	mW
Junction temperature	Tj	150	°C
Storage temperature	Tstg	–55 to +150	°C

Note: 1. Four device total, See Fig.2.

Electrical Characteristics *¹

(Ta = 25°C)

Item	Symbol	Min	Typ	Max	Unit	Test Condition
Zener voltage	V _z	6.47	—	7.00	V	I _z = 5 mA, 40ms pulse
Reverse current	I _R	—	—	0.5	μA	V _R = 3.5V
Capacitance	C	—	—	25	pF	V _R = 0V, f = 1 MHz
Dynamic resistance	r _d	—	—	30	Ω	I _z = 5 mA
ESD-Capability * ² * ³	—	25	—	—	kV	C =150 pF, R = 330 Ω, Both forward and reverse direction 10 pulse

- Notes 1. Per one device.
2. Failure criterion ; I_R > 0.5 μA at V_R = 3.5 V.
3. Between cathode and anode.

Month Code

Month of Manufacture	Month Code	Month of Manufacture	Month Code
January	A	July	G
February	B	August	H
March	C	September	J
April	D	October	K
May	E	November	L
June	F	December	M

Main Characteristic

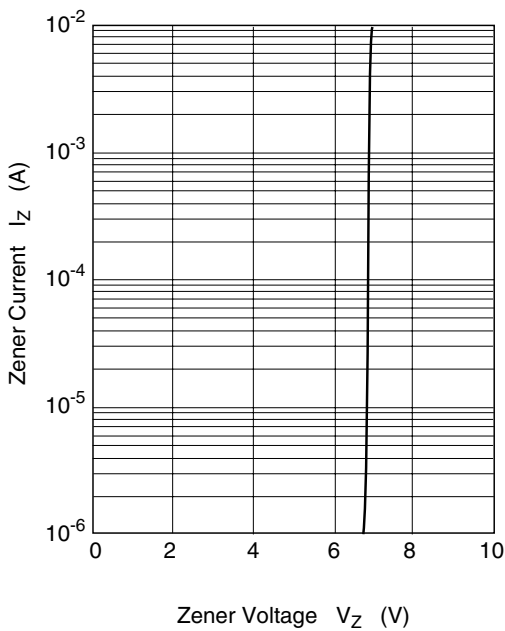


Fig.1 Zener current vs. Zener voltage

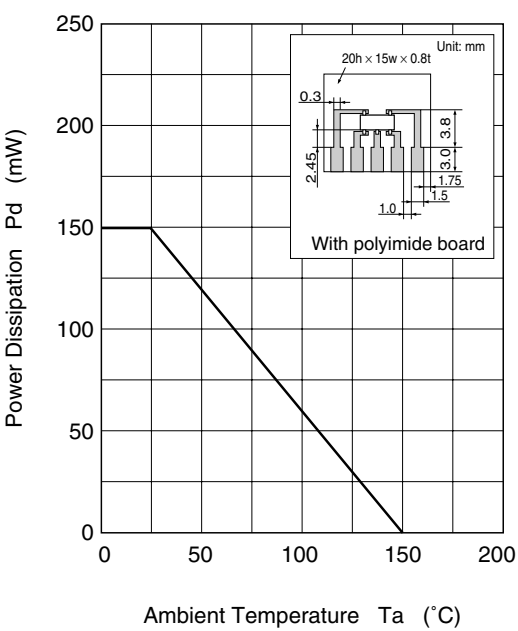


Fig.2 Power Dissipation vs. Ambient Temperature

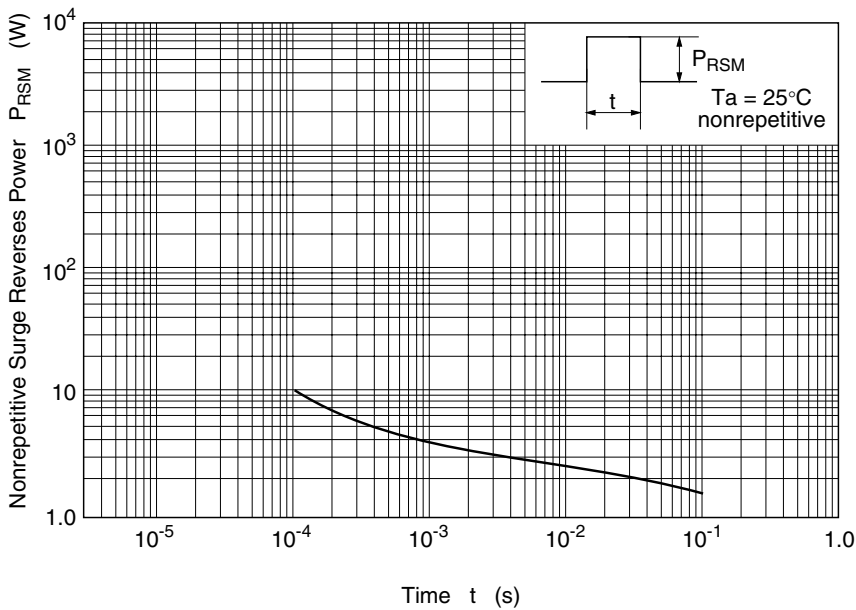


Fig.3 Surge Reverse Power Ratings

Main Characteristic

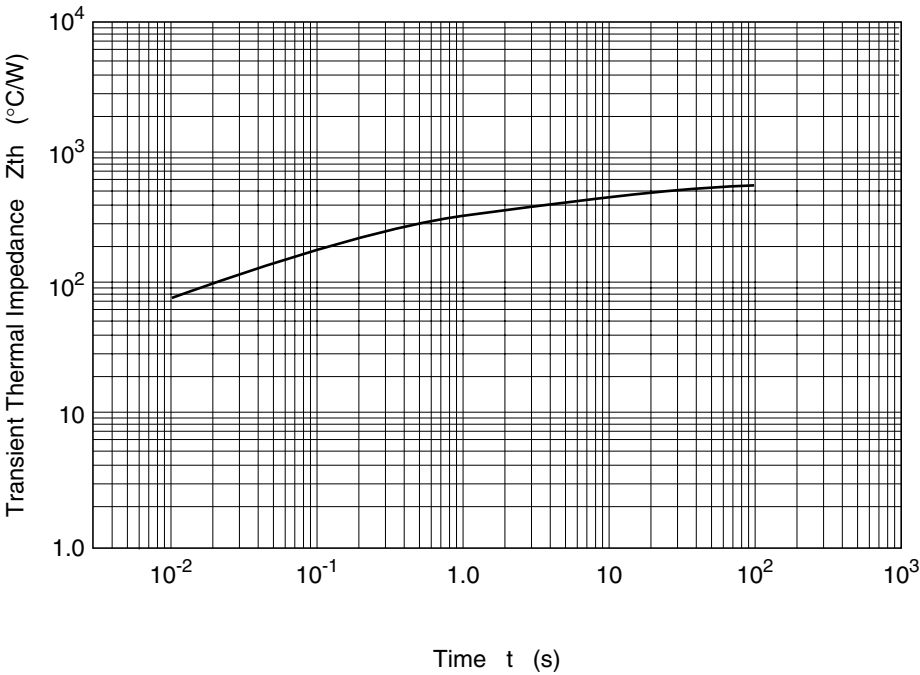
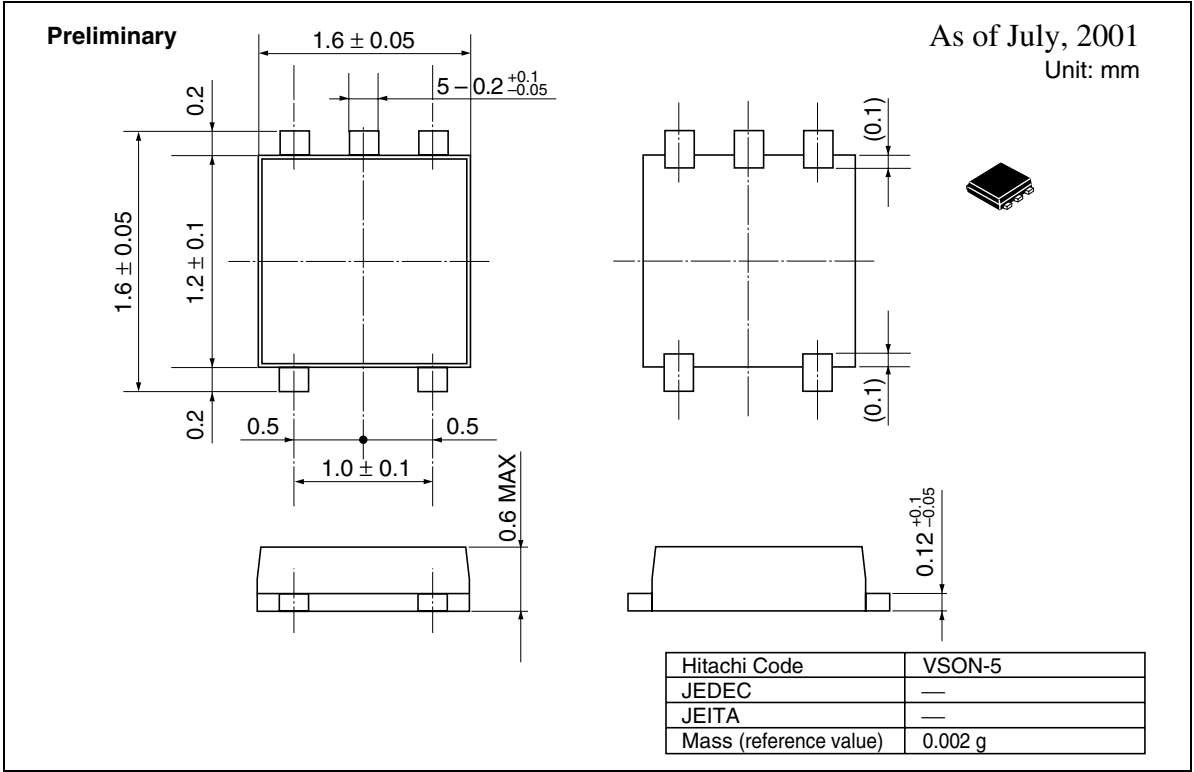


Fig.4 Transient Thermal Impedance

Package Dimensions



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